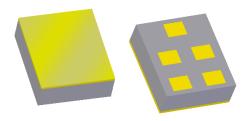
## **Applications**

• For Band 40 TD-LTE applications

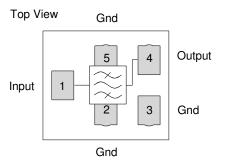


1.4 x 1.2 x 0.46 mm

### **Product Features**

- · Highly selective BAW filter achieving low insertion loss over full bandwidth and operating conditions
- Performance -20 to +90 ℃
- · Excellent Wi-Fi rejection
- Single-ended operation
- Ceramic chip-scale Package (CSP)
- Small Size
- Hermetic RoHS compliant, Pb-free

## **Functional Block Diagram**



#### **General Description**

885069 is a Band 1 Uplink filter for general purpose wireless applications. This filter was specifically designed in a 3x3 mm hermetic package for base station applications and is part of our wide portfolio of RF filters in the same package.

885069 has low insertion loss, coupled with high attenuation and good power handling, making this filter a natural choice for our customers uplink RF filtering needs and other general purpose applications.

885069 require no matching components, making filter implementation easy.

# **Pin Configuration**

Pin No.	Label
1	Input
4	Output
2,3,5	Ground

# **Ordering Information**

Part No.	Description
885069	Packaged Part
885069-EVB	Evaluation board

Standard T/R size = 10,000 units/reel

RFMD + TriQuint = Qorvo

#### Absolute Maximum Ratings

Parameter	Rating
Storage Temperature (1)	–40 to +90 ℃
Operable Temperature (2)	–20 to +90 ℃
RF Input Power (3)	+27 dBm

- 1. Operation of this device outside the parameter ranges given may cause permanent damage.
- 2. Specifications are not guaranteed over all operable conditions.
- 3. Input Power with applied CW signal in passband

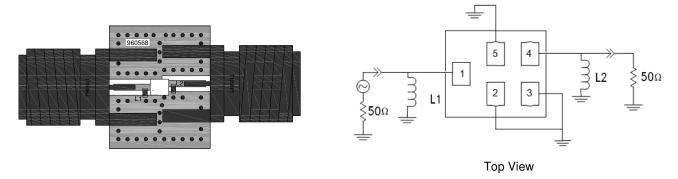
# Electrical Specifications (1)

		–20 °C +25 °C			+90 ℃				
Parameter	Conditions	Min	Max	Min	Typ (2)	Max	Min	Max	Unit
Insertion Loss	2300 – 2395 MHz	-	3.0	-	1.3	2.7	-	2.7	dB
Insertion Loss	2395-2400 MHz	-	2.2	-	1.8	3.0	-	3.2	dB
Input/output VSWR	2300 – 2400 MHz	-	2.0:1	-	1.4:1	2.0:1	-	2.0:1	-
Passband Ripple	2300 – 2400 MHz	-	1.7	-	1.1	1.7	-	1.7	dB
	10-1574 MHz	30	-	30	47	-	30	-	dB
	1574 – 1577 MHz	30	-	30	33	-	30	-	dB
	1577 – 1680 MHz	30	-	30	33	-	30	-	dB
	1845 – 1880 MHz	28	-	28	31	-	28	-	dB
	2110-2170 MHz	28	-	28	32	-	28	-	dB
Attenuation	2420 –2427 MHz	8	-	15	49	-	45	-	dB
	2427-2460 MHz	45	-	45	57	-	45	-	dB
	2460 – 2500 MHz	38	-	38	50	-	38	-	dB
	4600 – 4800 MHz	28	-	28	32	-	28	-	dB
	6900 – 7200 MHz	20	-	20	23	-	20	-	dB
	2422-7200 MHz <sup>(3)</sup>	20	-	20	23	-	20	-	dB
Source/Load Impedance <sup>(4)</sup>	Single-ended	-	-	-	50	-	-	-	Ω

- 1. All specifications are based on the TriQuint schematic for the main reference design shown on page 3.
- 2. Typical values are derived through integration of the linear s-parameter over the indicated band at the specified temperature.
- 3. Integration of the linear s-parameter over an 18 MHz sliding frequency span.
- 4. This is the optimum impedance in order to achieve the performance shown



#### 885069 Evaluation Board



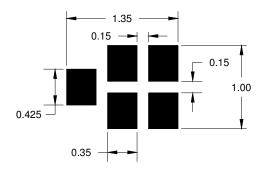
#### Notes:

- 1. Impedance matching required.
- 2. Top, middle & bottom layers: 1/2 oz copper, Substrates: FR4 dielectric, .062" thick, Finish plating: Nickel: 3-8 µm thick, Gold: .03-.2 μm thick, Hole plating: Copper min .0008 μm thick

#### Bill of Material - 885069-EVB

Reference Des.	Value	Description	Manuf.	Part Number
L1	3.9 nH	Chip Inductor, 0201, +/- 0.1nH	Murata	LQP03TN3N9H00
L2	4.3 nH	Chip Inductor, 0201, +/- 0.1nH	Murata	LQP03TN4N3H00
PCB	N/A	3-layer	Multiple	960568

# **PCB Mounting Pattern**



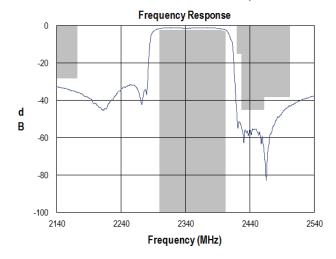
#### Notes:

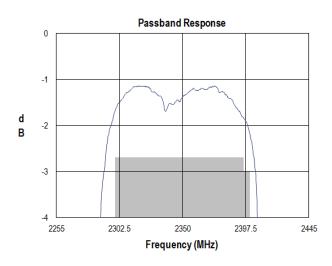
- 1. Black indicates metalized area
- 2. This footprint represents a recommendation only
- 3. For solder pad recommendation see mechanical information
- 4. Dimensions shown are nominal in millimeters

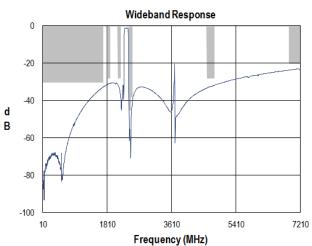


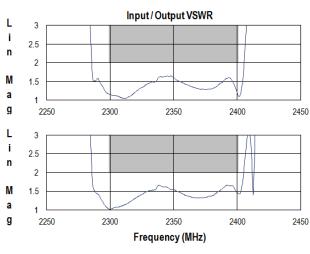
### **Measured Performance Plots**

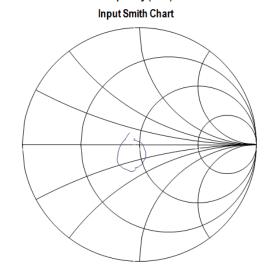
Test conditions unless otherwise noted: Temp= +25 °C

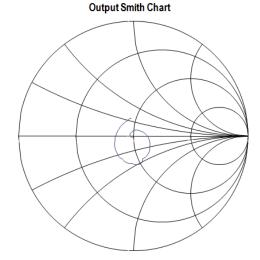






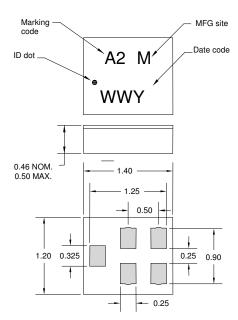








### Package Information, Marking and Dimensions



Package Style: CSP-5CT

Dimensions: 1.4 x 1.2 x 0.46 mm

Body: Al<sub>2</sub>O<sub>3</sub> ceramic

Lid: Kovar, Au over Ni plating

Terminations: Au plating 0.5 - 1.0 µm, over a 2-6 µm Ni plating

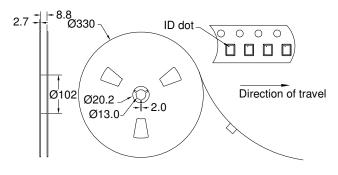
The date code consists of: WW = 2 digit week, Y = last digit of year M = manufacturing site code

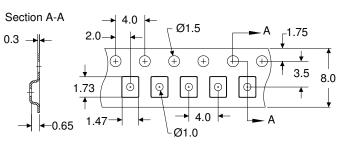
#### Notes:

- 1. All dimensions shown are typical in millimeters
- 2. All tolerances are ± 0.05 mm except overall length and width
- 3. An asterisk (\*) in front of the marking code indicates prototype.

# **Tape and Reel information**

Standard T/R size = 10,000 units/reel. All dimensions are in millimeters







# **Product Compliance Information**

#### **ESD Sensitivity Ratings**



Caution! ESD-Sensitive Device

ESD Rating: Class 1C Value: 1800 V

Test: Electrostatic Discharge Sensitivity Testing,

Human Body Model (HBM) - component level

Standard: ESDA/JEDEC JS-001-2012

ESD Rating: Class C Value: 400 V

Test: Machine Model (MM)

Standard: JEDEC Standard JESD22-A115

#### **MSL Rating**

Not applicable. Hermetic package.

#### **Solderability**

Compatible with both lead-free (260 °C maximum reflow temperature) and tin/lead (245 °C maximum reflow temperature) soldering processes.

Refer to **Soldering Profile** for recommended guidelines.

#### **RoHs Compliance**

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C<sub>15</sub>H<sub>12</sub>Br<sub>4</sub>0<sub>2</sub>) Free
- PFOS Free
- SVHC Free

#### **Contact Information**

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about TriQuint:

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For technical questions and application information: Email: flapplication.engineering@tqs.com

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